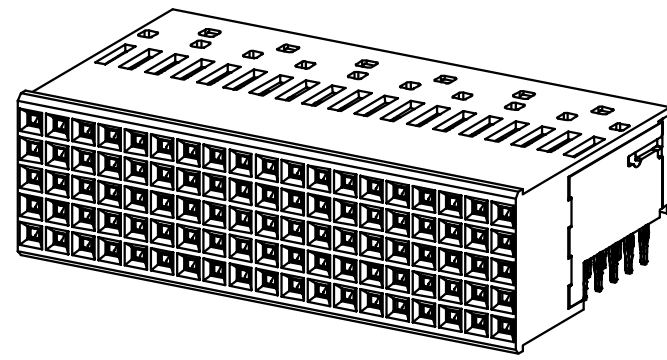
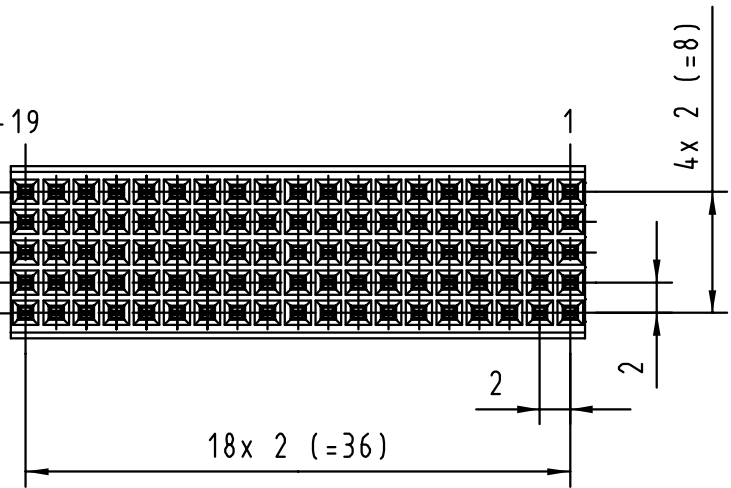


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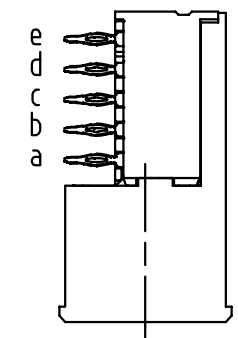
Position  
position

e  
d  
c  
b  
a

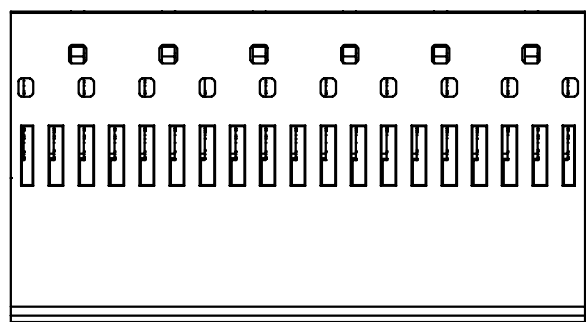
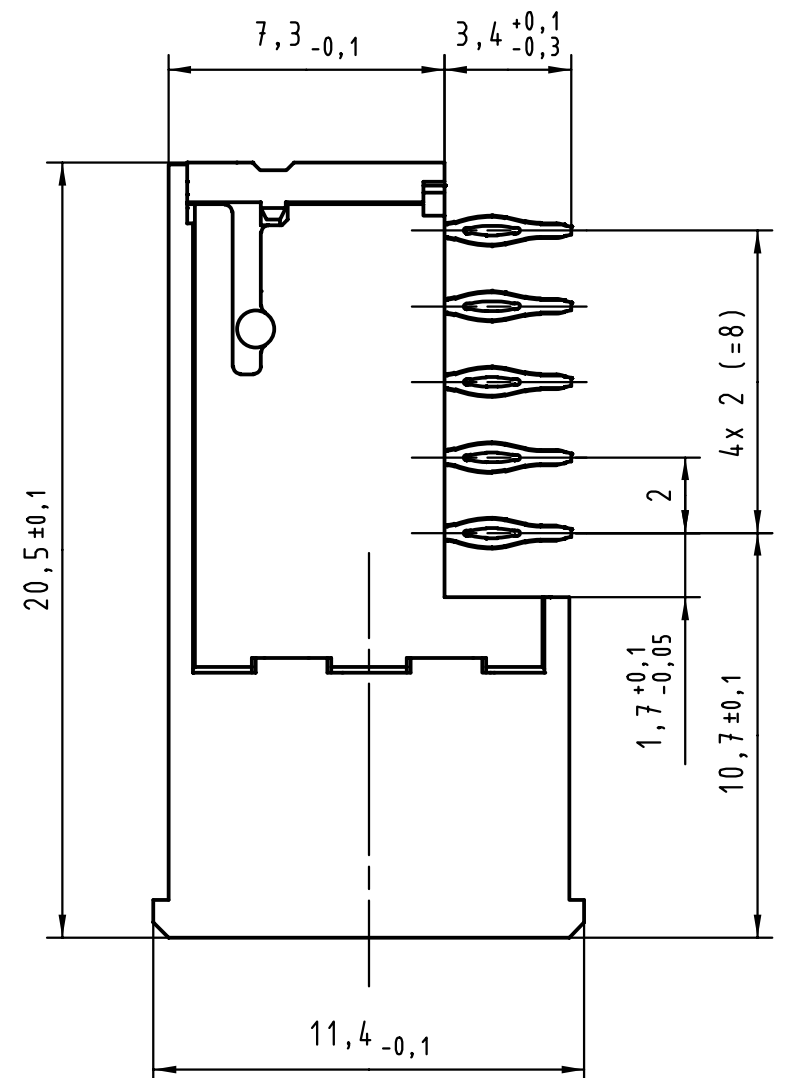
Reihe  
row



Reihe  
row

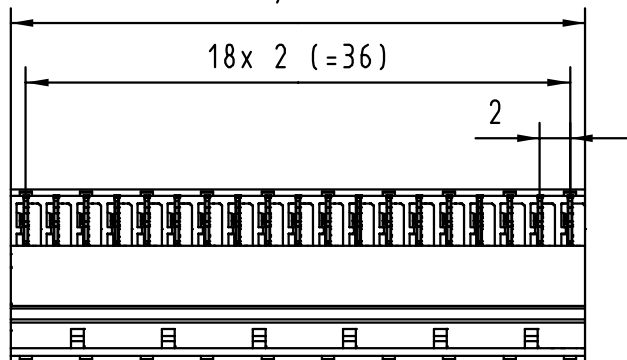


5:1



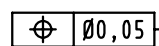
37,9<sup>+0,1</sup>

18x 2 (=36)



**Lochbild  
Board drillings**

alle Löcher  
all holes



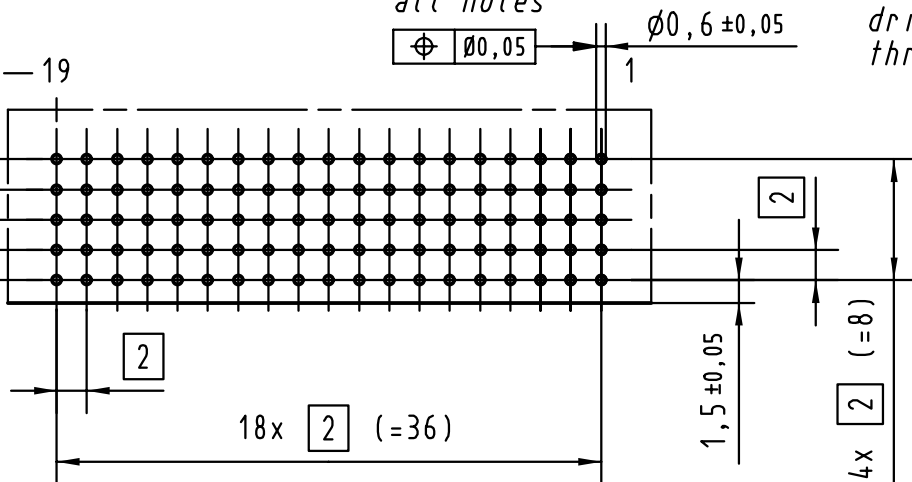
Ø 0,6 ± 0,05

Bohrlochdurchmesser:  $\phi 0,7 \pm 0,025$  mm  
 Lochdurchmesser (mit Oberfläche):  $\phi 0,6 \pm 0,05$  mm  
 drill hole dia.:  $\phi 0,7 \pm 0,025$  mm  
 through hole dia. (after plating):  $\phi 0,6 \pm 0,05$  mm

Position  
position

e  
d  
c  
b  
a

Reihe  
row



17 25 095 4101	-	min. 0,76 $\mu$ m (30 $\mu$ m) Au über/over min. 1,27 $\mu$ m (50 $\mu$ m) Ni
17 25 095 2101	2	Au über/over Ni
17 25 095 1101	1	Au über/over Ni
Bestell-Nr. Part-No.	Anforderungsstufe nach IEC performance level per IEC	Kontaktoberfläche Contact Plating per IEC

		Techn. Character.		Nicht tolerierte Maß/Free size tolerances siehe / see IEC 61076-4-101	
				Maßstab/Scale 2:1 (5:1)	
26047	27.05.99	Hm	Detail.	30.10.97	Hm
25017	22.09.98	Hm	Insp.	30.10.97	Ko
24594	07.08.98	Hm	Stand.		
22833			HARTING KGaA D-32339 ESPELKAMP		
Mod.	Dat.	Name			
					TB 17 25 095 x101 Sub.
					Blatt/ page